

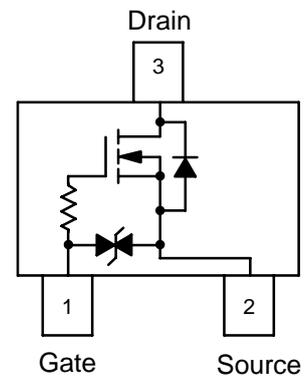
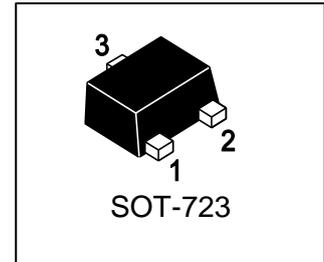
LNTK3043NT5G

S-LNTK3043NT5G

20 V, 285 mA, N-Channel Power MOSFET

1. FEATURES

- Enables High Density PCB Manufacturing
- 44% Smaller Footprint than SC-89 and 38% Thinner than SC-89
- Low Voltage Drive Makes this Device Ideal for Portable Equipment
- Low Threshold Levels, $V_{GS(TH)} < 1.3\text{ V}$
- Low Profile ($< 0.5\text{ mm}$) Allows It to Fit Easily into Extremely Thin Environments such as Portable Electronics
- Operated at Standard Logic Level Gate Drive, Facilitating Future Migration to Lower Levels Using the Same Basic Topology
- These are Pb-Free Devices
- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.



2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LNTK3043NT5G	KA	8000/Tape&Reel

3. MAXIMUM RATINGS($T_a = 25^\circ\text{C}$)

Parameter		Symbol	Limits	Unit
Drain-to-Source Voltage		V_{DSS}	20	V
Gate-to-Source Voltage		V_{GS}	± 10	V
Continuous Drain Current (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	255	mA
		$T_A = 85^\circ\text{C}$	185	
	$t \leq 5\text{ s}$	$T_A = 25^\circ\text{C}$	285	
Power Dissipation(Note 1)	Steady State	$T_A = 25^\circ\text{C}$	440	mW
	$t \leq 5\text{ s}$		545	
Continuous Drain Current (Note 2)	Steady State	$T_A = 25^\circ\text{C}$	210	mA
		$T_A = 85^\circ\text{C}$	155	
Power Dissipation(Note 2)		$T_A = 25^\circ\text{C}$	310	mW
Pulsed Drain Current($t_p = 10\ \mu\text{s}$)		I_{DM}	400	mA
Source Current (Body Diode) (Note 2)		I_S	286	mA
Operating Junction and Storage Temperature		T_J, T_{stg}	$-55 \sim +150$	$^\circ\text{C}$
Lead Temperature for Soldering Purposes (1/8 " from case for 10 s)		T_L	260	$^\circ\text{C}$

4. THERMAL CHARACTERISTICS

Parameter		Symbol	Limits	Unit
Thermal Resistance-Junction to Ambient	Steady State(Note 1)	R θ JA	280	°C/W
	t = 5 s(Note 1)		228	
	Steady State(Note 2)		400	

1.Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces)

2.Surface-mounted on FR4 board using the minimum recommended pad size.

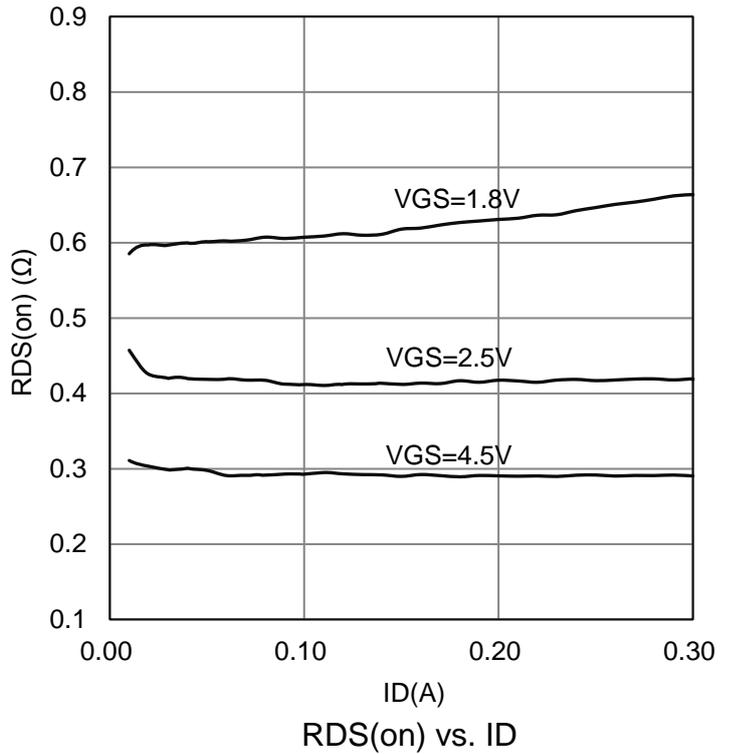
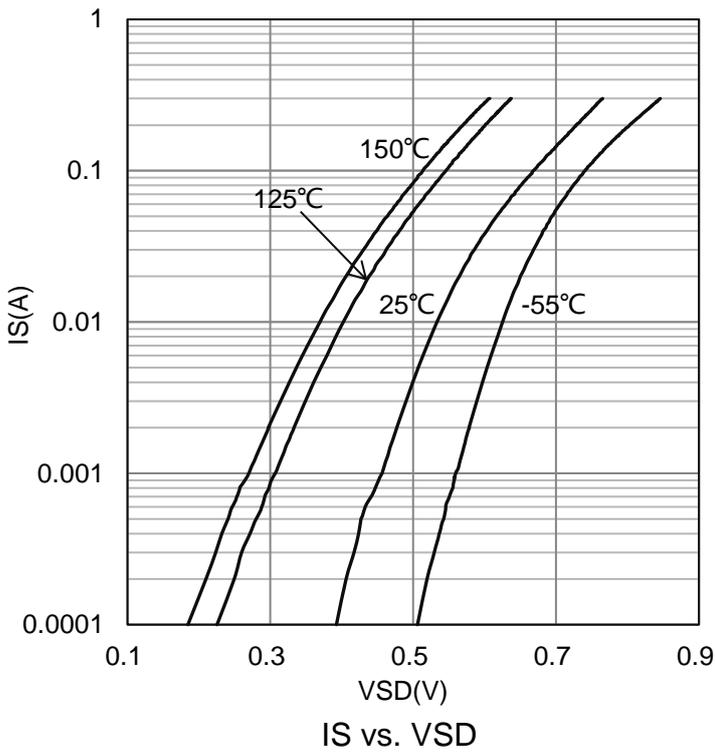
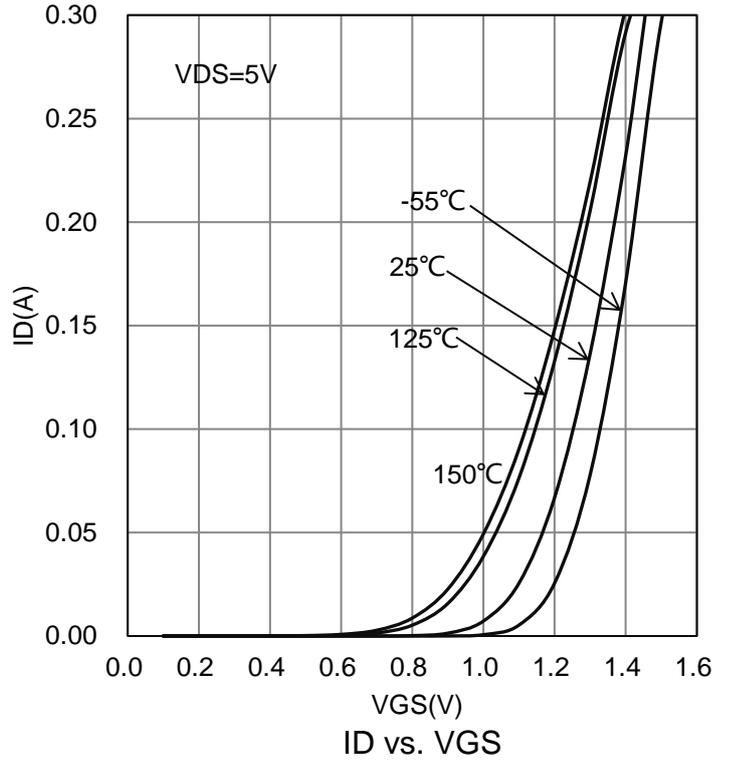
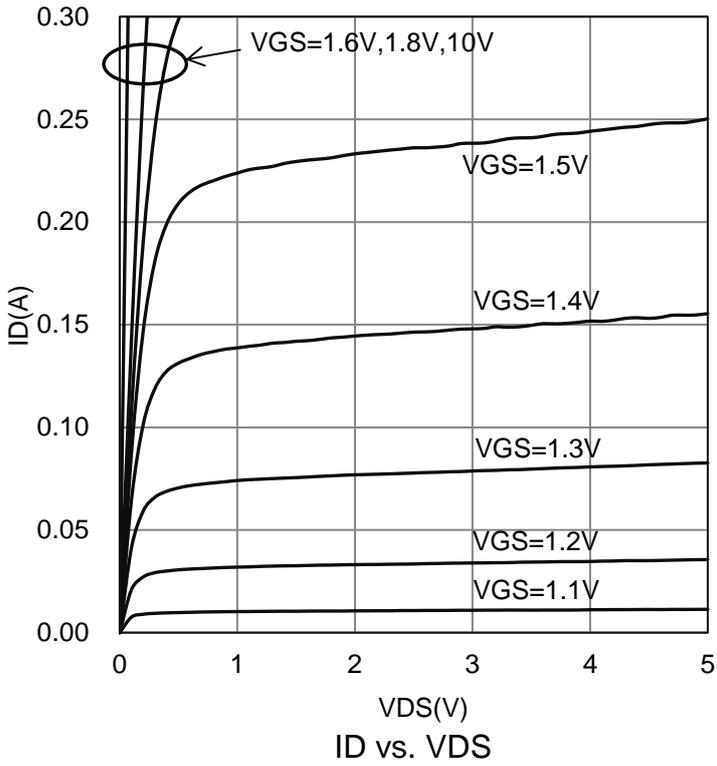
5. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Static					
Drain-Source Breakdown Voltage (VGS = 0, ID = 100 μ A)	VBRDSS	20	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	VBRDSS/TJ	-	27	-	mV/°C
Zero Gate Voltage Drain Current (VGS = 0, VDS = 16 V, TJ = 25°C) (VGS = 0, VDS = 16 V, TJ = 125°C)	IDSS	-	-	1 10	μ A
Gate-Body Leakage Current (VDS = 0 V, VGS = \pm 5 V)	IGSS	-	-	\pm 1	μ A
Gate Threshold Voltage (VDS = VGS, ID = 250 μ A)	VGS(th)	0.4	-	1.3	V
Gate Threshold Temperature Coefficient	VGS(TH)/TJ	-	-2.4	-	mV/°C
Static Drain-Source On-State Resistance (VGS = 4.5V, ID = 10 mA) (VGS = 4.5V, ID = 255 mA) (VGS = 2.5 V, ID = 1 mA) (VGS = 1.8 V, ID = 1 mA) (VGS = 1.65 V, ID = 1 mA)	RDS(on)	-	1.5 1.6 2.4 5.1 6.8	3.4 3.8 4.5 10 15	Ω
DYNAMIC					
Input Capacitance	(VGS=0 V, f=1 MHz, VDS=10 V)	Ciss	-	55	pF
Output Capacitance		Coss	-	11.5	
Reverse Transfer Capacitance		Crss	-	7	
Turn-On Delay Time	(VGS = 4.5 V, VDD = 5 V, ID = 10 mA, RG = 6 Ω)	td(on)	-	4.8	ns
Rise Time		tr	-	2.4	
Turn-Off Delay Time		td(off)	-	32	
Fall Time		tf	-	69	
Diode Forward Voltage (VGS = 0 V, IS = 286 mA)	TJ = 25°C TJ = 125°C	VSD	-	0.83 0.69	V
Reverse Recovery Time	(VGS=0 V, VDD =20 V, dISD/dt=100 A/ μ s, IS=286 mA)	tRR	-	9.1	ns
Charge Time		ta	-	7.1	
Discharge Time		tb	-	2.0	
Reverse Recovery Charge		QRR	-	3.7	

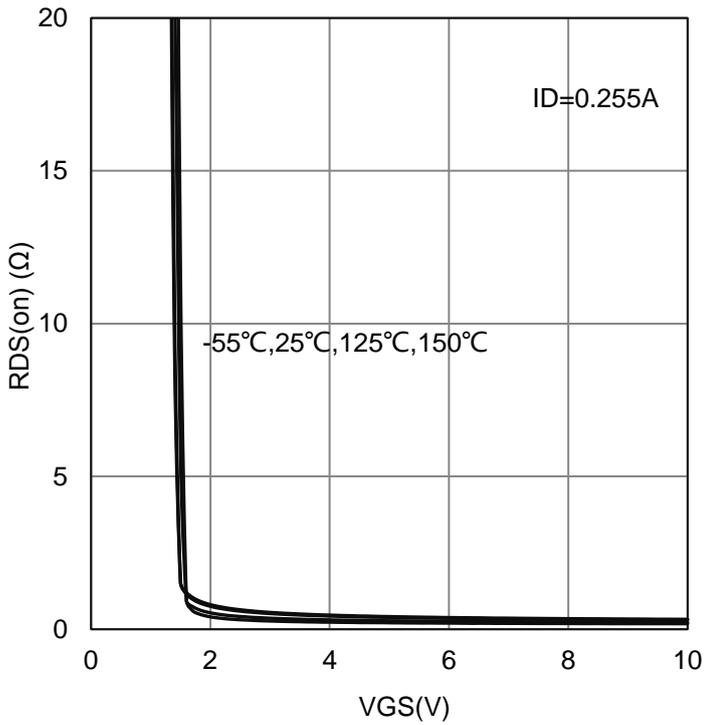
3.Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

4.Switching characteristics are independent of operating junction temperatures

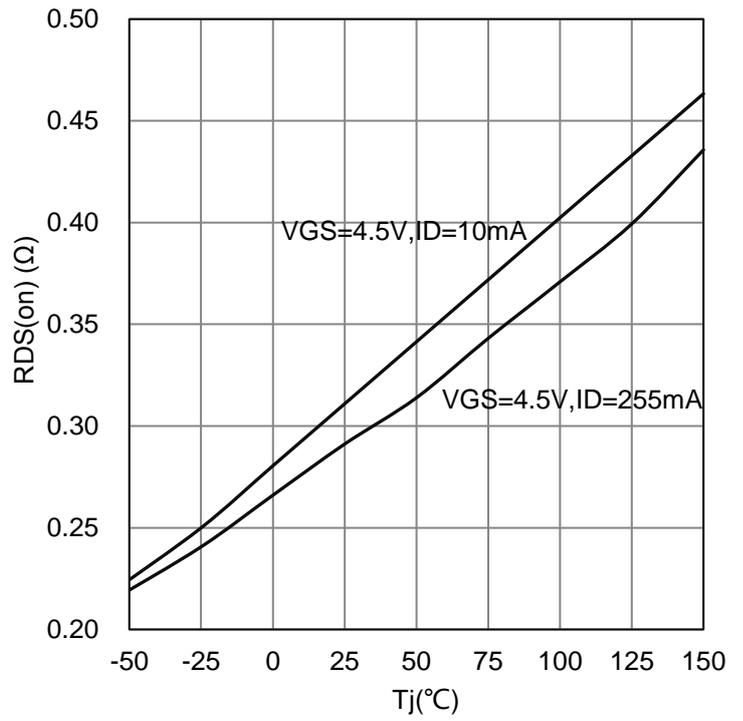
6. ELECTRICAL CHARACTERISTICS CURVES



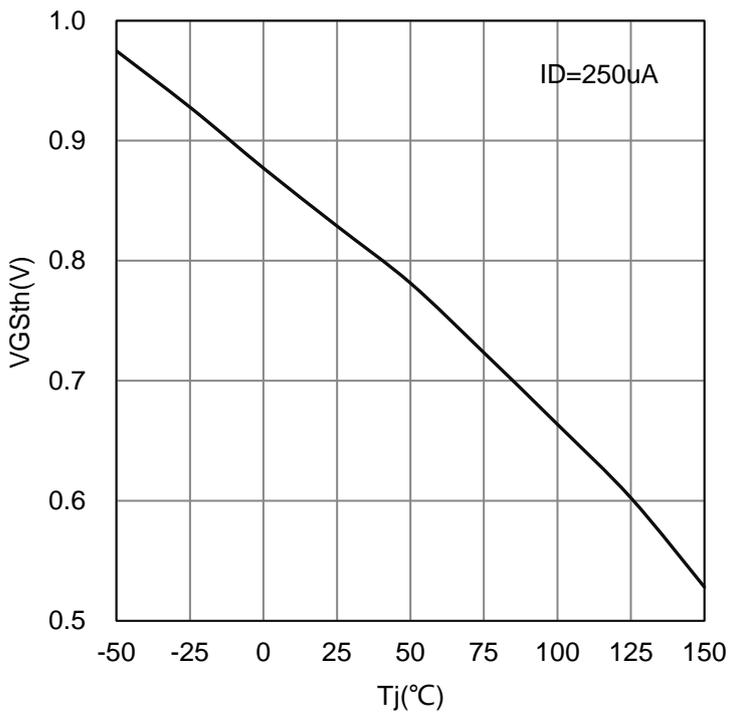
6.ELECTRICAL CHARACTERISTICS CURVES(Con.)



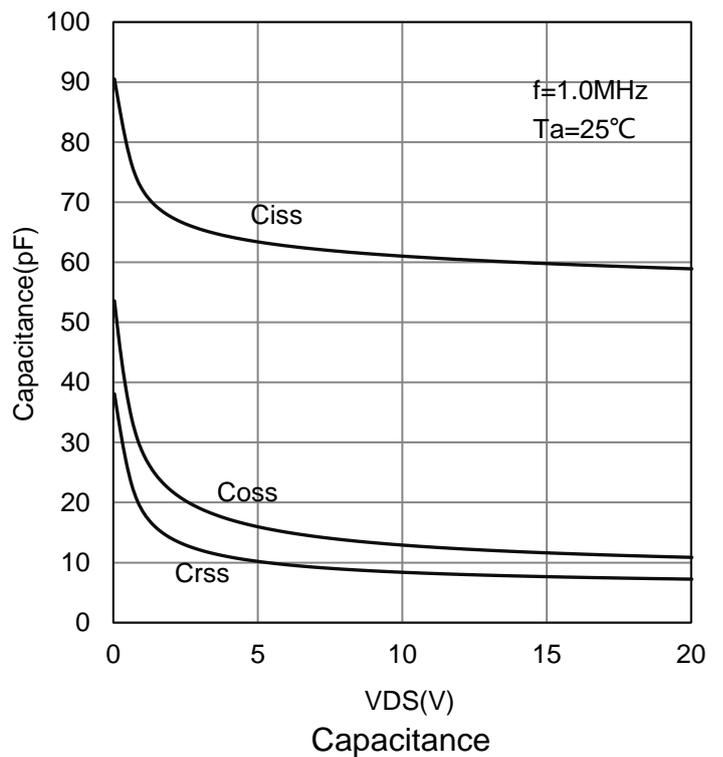
RDS(on) vs. VGS



RDS(on) vs. Tj

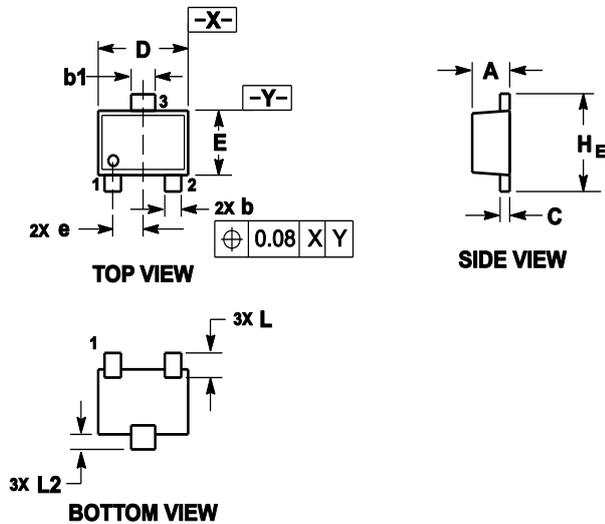


VGSth vs. Tj



Capacitance

7. OUTLINE AND DIMENSIONS

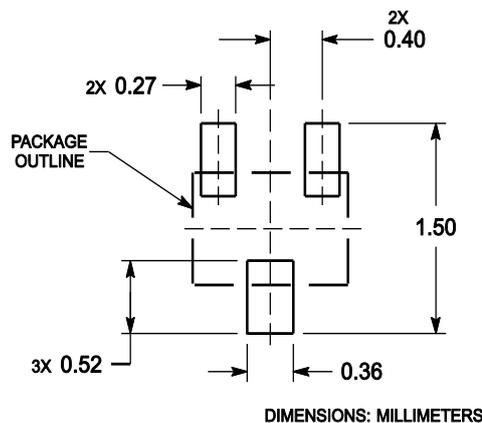


Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.45	0.50	0.55	0.018	0.020	0.039
b	0.15	0.21	0.27	0.006	0.008	0.011
b1	0.25	0.31	0.37	0.010	0.012	0.015
C	0.07	0.12	0.17	0.003	0.005	0.007
D	1.15	1.20	1.25	0.045	0.047	0.049
E	0.75	0.80	0.85	0.030	0.031	0.033
e	0.40REF			0.016REF		
H _E	1.15	1.20	1.25	0.045	0.047	0.049
L	0.29REF			0.011REF		
L ₂	0.15	0.20	0.25	0.006	0.008	0.010

8. SOLDERING FOOTPRINT



DISCLAIMER

- Curve guarantee in the specification. The curve of test items with electric parameter is used as quality guarantee. The curve of test items without electric parameter is used as reference only.
- Before you use our Products for new Project, you are requested to carefully read this document and fully understand its contents. LRC shall not be in any way responsible or liable for failure, malfunction or accident arising from the use of any LRC's Products against warning, caution or note contained in this document.
- All information contained in this document is current as of the issuing date and subject to change without any prior notice. Before purchasing or using LRC's Products, please confirm the latest information with a LRC sales representative.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for [MOSFET](#) category:

Click to view products by [Leshan](#) manufacturer:

Other Similar products are found below :

[614233C](#) [648584F](#) [MCH3443-TL-E](#) [MCH6422-TL-E](#) [FDPF9N50NZ](#) [NTNS3A92PZT5G](#) [IRFD120](#) [IRFF430](#) [JANTX2N5237](#) [2N7000](#)
[AOD464](#) [2SK2267\(Q\)](#) [2SK2545\(Q,T\)](#) [405094E](#) [423220D](#) [MIC4420CM-TR](#) [VN1206L](#) [614234A](#) [715780A](#) [SSM6J414TU,LF\(T](#) [751625C](#)
[IPS70R2K0CEAKMA1](#) [BSF024N03LT3 G](#) [PSMN4R2-30MLD](#) [TK31J60W5,S1VQ\(O](#) [2SK2614\(TE16L1,Q\)](#) [DMN1017UCP3-7](#)
[EFC2J004NUZTDG](#) [FCAB21350L1](#) [P85W28HP2F-7071](#) [DMN1053UCP4-7](#) [NTE2384](#) [NTE2969](#) [NTE6400A](#) [DMC2700UDMQ-7](#)
[DMN2080UCB4-7](#) [DMN61D9UWQ-13](#) [US6M2GTR](#) [DMN31D5UDJ-7](#) [SSM6P54TU,LF](#) [DMP22D4UFO-7B](#) [IPS60R3K4CEAKMA1](#)
[DMN1006UCA6-7](#) [DMN16M9UCA6-7](#) [STF5N65M6](#) [IRF40H233XTMA1](#) [IPSA70R950CEAKMA1](#) [IPSA70R2K0CEAKMA1](#) [STU5N65M6](#)
[C3M0021120D](#)